

Amendments to the Claims:

The following listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

1. (currently amended) An optoelectronic component comprising:
 - a heat sink;
 - a carrier thermally conductively connected to the heat sink;
 - a semiconductor arrangement which emits or receives electromagnetic radiation and which is arranged on the carrier;
 - external electrical connections which are connected to the semiconductor arrangement, wherein the external electrical connections are arranged in electrically insulated fashion on the heat sink at a distance from the carrier;
 - a basic housing arranged on the heat sink,
 - wherein the semiconductor arrangement and the carrier are arranged in a cavity defined in the basic housing, and wherein the cavity in the basic housing comprises an inner side which obliquely faces the semiconductor arrangement and forms a first reflective area for a portion of the electromagnetic radiation; and
 - a reflective filling compound provided between the semiconductor arrangement and the inner side of the basic housing, the reflective filling material comprising a concave curved surface extending from the inner side of the basic housing to a top edge of the carrier and forming a second reflective area for another portion of the electromagnetic radiation.

2. (previously presented) The optoelectronic component as claimed in claim 1, wherein the carrier contains a carrier substrate and an electrically insulating layer arranged thereon.

3. (previously presented) The optoelectronic component as claimed in claim 2, wherein the semiconductor arrangement and the electrically insulating layer have an electrically conductive layer arranged therebetween which is connected to one of the external electrical connections.

4. (previously presented) The optoelectronic component as claimed in claim 1, wherein the semiconductor arrangement contains a semiconductor chip.

5. (previously presented) The optoelectronic component as claimed in claim 1, wherein the external electrical connections include conductor tracks on a printed circuit board.

6. (previously presented) The optoelectronic component as claimed in claim 1, wherein conductor tracks on different printed circuit boards arranged above one another form the electrical connection and are connected to one another by plated-through holes defined in the printed circuit boards.

7. (previously presented) The optoelectronic component as claimed in claim 2, wherein the carrier substrate has at least one material with good thermal conductivity from the group comprising Si, diamond-coated Si, diamond, SiC, AlN and BN.

8. (previously presented) The optoelectronic component as claimed in claim 2, wherein the electrically insulating layer comprises SiO₂.

9. (previously presented) The optoelectronic component as claimed in claim 1, wherein the semiconductor arrangement is attached to the carrier by a metal solder or a thermally or electrically conductive adhesive.

10. (previously presented) The optoelectronic component as claimed in claim 1, wherein the carrier is attached to the heat sink by a metal solder or a thermally conductive adhesive.

11. (canceled)

12. (previously presented) The optoelectronic component as claimed in claim 1, wherein the cavity of the basic housing contains only one semiconductor arrangement.

13. (canceled)

14. (canceled)

15. (previously presented) The optoelectronic component as claimed in claim 1, wherein the filling compound contains TiO₂ or an epoxy resin filled with TiO₂ particles.

16. (previously presented) The optoelectronic component as claimed in claim 1, wherein the semiconductor arrangement is at least partly encapsulated by a radiation-pervious encapsulation compound.

17. (previously presented) The optoelectronic component as claimed in claim 1, wherein at least some of the external connections are arranged between the basic housing and the heat sink.

18. (previously presented) The optoelectronic component as claimed in claim 1, wherein an electrical power consumption of the optoelectronic component is at least 0.5 W.

19. (previously presented) The optoelectronic component as claimed in claim 1, wherein an electrical power consumption of the optoelectronic component is at least 1 W.

20. (previously presented) The optoelectronic component as claimed in claim 1, wherein an electrical power consumption of the optoelectronic component is at least 3 W.

21. (previously presented) The optoelectronic component as claimed in claim 1, wherein the optoelectronic component has a base area not greater than 1 cm^2 .

22. (previously presented) A component-based module, wherein the module has a plurality of optoelectronic components as claimed in claim 1.

23. (previously presented) A component-based module having a plurality of optoelectronic components as claimed in claim 1, wherein at least some of the optoelectronic components are electrically conductively connected to one another by conductor tracks.

24. (previously presented) The component-based module as claimed in claim 22, wherein the optoelectronic components are arranged in the form of a matrix and at least some of the optoelectronic components are connected in series.

25. (canceled)